

ESD PROTECTION DEVICE

STAND-OFF VOLTAGE – 3.3 Volts POWER DISSIPATION – 90 WATTS

GENERAL DESCRIPTION

L09ESD3V3CP2 is designed to replace multilayer varistors (MLVs) in portable applications where low operating voltage is vital. They offer superior electrical characteristics such as lower clamping voltage and no device degradation when compared to MLVs. They are designed

to protect sensitive semiconductor components from damage or upset due to electrostatic discharge (ESD), lightning, electrical fast transients (EFT), and cable discharge events (CDE).

FEATURES

- Protects one power or I/O line
- Max. peak pulse power : Ppp = 90W at tp = 8/20 us.
- Low clamping voltage
- IEC 61000-4-2, level 4 (ESD), > ±15KV (air); > ±8KV (contact)

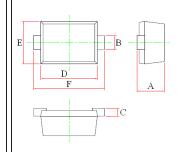
APPLICATION

- · Cellular Handsets & Accessories
- Notebooks & Handhelds
- Portable Instrumentation
- Digital Cameras
- Peripherals
- MP3 Players

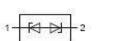
MECHANICAL DATA

- Case Material: "Green" molding compound UL flammability classification 94V-0 (No Br.Sb, Cl)
- Terminals: Lead Free Plating (Matte Tin Finish), solderable per J-STD-002 and JESD22-B/02.
- Moisture Sensitivity: Leve 1 per J-STD-020C
- Component in accordance to RoHs 2002/95/E

SOD-923



SOD-923				
DIM.	MIN.	MAX.		
Α	0.36	0.41		
В	0.18	0.26		
С	0.08	0.14		
D	0.76	0.84		
Е	0.56 0.64			
F	0.92	1.08		
All Dimensions in millimeter				



PIN A SSIGNMENT		
1	Cathode	
2	Cathode	

MAXIMUM RATINGS (Tj= 25° unless otherwise noticed)

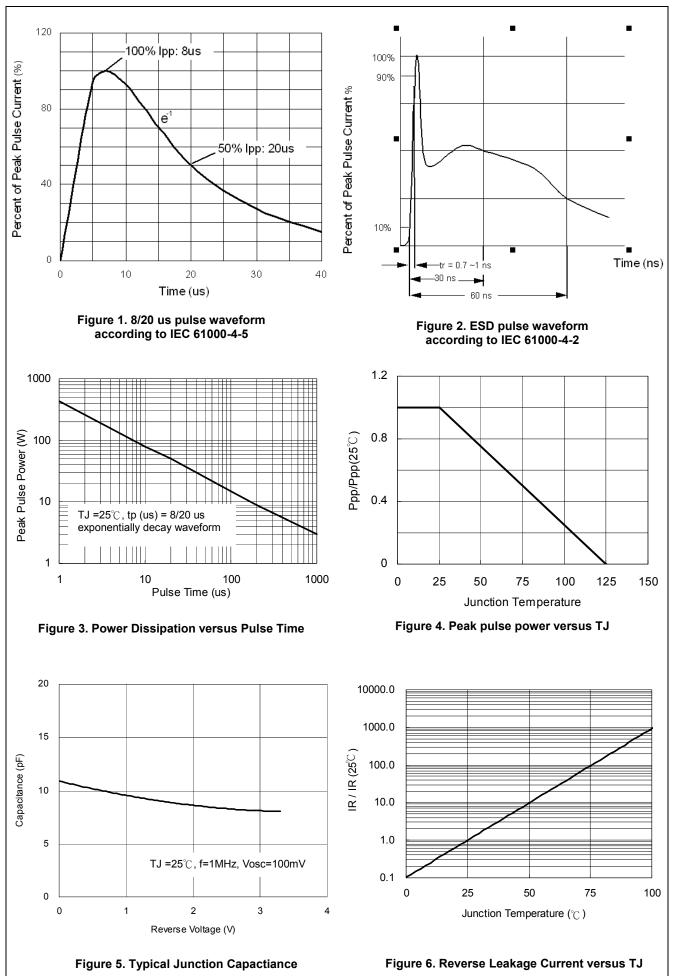
Rating		Value	Unit
Peak Pulse Power (tp = 8/20us)	Ppk	90	W
Peak Pulse Current (tp = 8/20us)		5	Α
Operating Junction Temperature Range		-55 to + 125	$^{\circ}\!\mathbb{C}$
Storage Temperature Range		-55 to + 150	$^{\circ}\!\mathbb{C}$
Soldering Temperature, t max = 10s		260	$^{\circ}\!\mathbb{C}$

ELECTRICAL CHARACTERISTICS (Tj= 25°C unless otherwise noticed)

Parameter	Symbol	Conditions	MIn	Тур	Max	Unit
Reverse standoff voltage	V_{RWM}				3.3	V
Punch Through Voltage	VPT	IsB = 2uA	3.5			V
Snap-Back Voltage	VsB	I _{SB} = 50 mA	2.8			V
Reverse leakage current	IRM	V _{DRM} = 3.3V		0.05	0.5	uA
Clamping Voltage	Vc	I_{PP} = 1A, tp = 8/20 μ s		6.0	8.0	٧
Clamping Voltage	V _C	$I_{PP} = 5 \text{ A}, \text{ tp} = 8/20 \mu \text{s}$		8.5	18	V
Junction capacitance	CJ	$V_R = 0V$, $f = 1MHz$		11	15	pF
				DEV. 0	Oat 2010	1/01040

REV. 0, Oct-2010, KSIR46







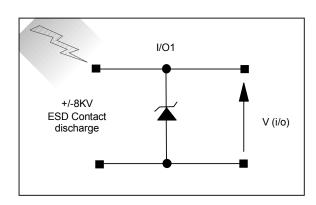
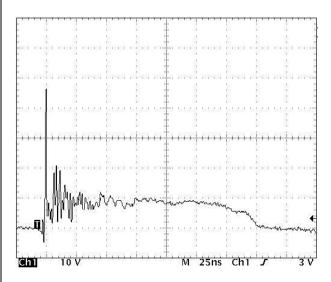


Figure 7. ESD Test Configuration



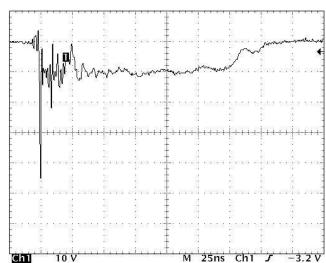
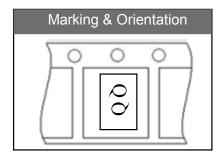


Figure 8. Clamped +8 kV ESD voltage waveform

Figure 9. Clamped -8 kV ESD voltage waveform



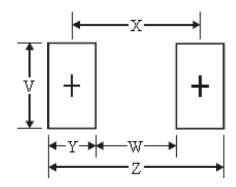
Marking & Orientation



Packaging Information

DEVICE	Q'TY/REEL	REEL DIA.	Q'TY/BOX	Q'TY/CARTON
	(PCS)	(INCH)	(PCS)	(PCS)
L09ESD3V3CP2	8000	7	120K	480K

SOD-923 Soldering Pad Layout



Dim.	Millimeters	Inches	
Z	1.20	0.047	
X	0.90	0.035	
W	0.60	0.023	
Y	0.30	0.011	
V	0.40	0.015	



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